METHOD AND APPARATUS FOR HIGH ELECTRICAL AND THERMAL PERFORMANCE BALL GRID ARRAY PACKAGE

Abstract

A high electrical and thermal performance thick film ceramic ball grid array package with a laser cut die cavity is presented. The thick film ceramic ball grid array package may have a thick film ceramic substrate with a first side and a second side with a heat spreader or a heat sink on the second side. An IC die may be attached to the heat spreader or heat sink through the laser cut die cavity and wire bonded to pads on the first side of the ceramic substrate. The thick film ceramic substrate may have one or more integrated passive components.

Fig. 1